

1. (Thrice Amended)

Sub
E1
D1

A method of manufacturing a thin film resistor with a moisture barrier comprising:

- depositing a non-tantalum metal film resistive layer on a thin film resistor substrate;
- attaching a thin film resistor termination on each end of the metal film resistive layer; and
- depositing the moisture barrier comprising a layer of tantalum pentoxide film directly overlaying and attaching to the metal film resistive layer to reduce failures due to electrolytic corrosion under powered moisture conditions.

15. (Twice Amended)

Sub
E2

A method of manufacturing a thin film resistor with a moisture barrier comprising:

- depositing a non-tantalum metal film resistive layer on a substrate;
- attaching a termination on each end of the metal film resistive layer;
- depositing a passivation layer directly overlaying and attaching to the metal film layer; and
- depositing the moisture barrier comprising a layer of tantalum pentoxide film directly overlaying and attaching to the passivation layer for reducing failures due to electrolytic corrosion under powered moisture conditions.